## PROCEDURES RE: MOTIONS TO AVOID LIENS PURSUANT TO 11 U.S.C § 522(f)

- Motion. A motion to avoid a judicial lien on real property must be filed on <u>Local Bankruptcy Form (LBF) 717.05</u>. A motion to avoid a lien on any other collateral under 11 U.S.C. § 522(f) must be in writing and state:
  - a. Name and address of lienholders whose liens are to be voided:
  - b. The subsection of § 522(f) under which relief is requested;
  - c. The nature of the security interests or liens;
  - d. The date upon which the security interests or liens were perfected;
  - e. A description of the collateral sufficient for identification;
  - f. The fair market value of the collateral;
  - g. A description of and the amounts due upon any other security interests or liens upon the collateral:
  - h. Description of nature and amount of exemptions impaired;
  - i. The present balance owing on the security interests or liens upon the collateral, excluding any precomputed interest or other unearned charges;
  - j. Extent to which fixing of the liens should be avoided; and
  - k. Any other facts which would be relevant in determining whether the motion should be granted.
- 2. **Notice of Motion**. The debtor must use the current version of LBF 717.
- 3. **Filing and Service of Motion and Notice of Motion**. The debtor must serve the motion and notice on all parties listed on the certificate of service of the notice and file them with the clerk.
- 4. **Objection.** If any party wishes to object to the motion, the party must file a written objection with the clerk by the deadline stated in the notice of motion.
- 5. **Hearing**. If a timely objection is filed, the court will decide whether a hearing will be required. If so, a notice of hearing will be issued by the clerk.
- Failure to Respond. If no timely objection is filed, the court may sign an order, submitted by the debtor on <u>LBF 717.07</u> if the lien is a judicial lien on real property, granting the motion.
- 7. **Order.** An order avoiding a judicial lien on real property must be submitted on <u>LBF 717.07.</u>